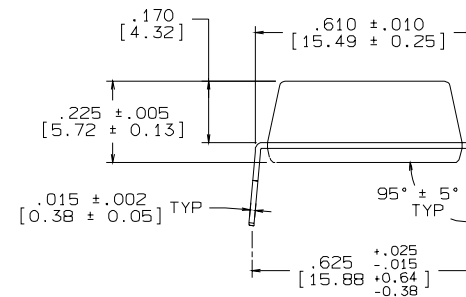
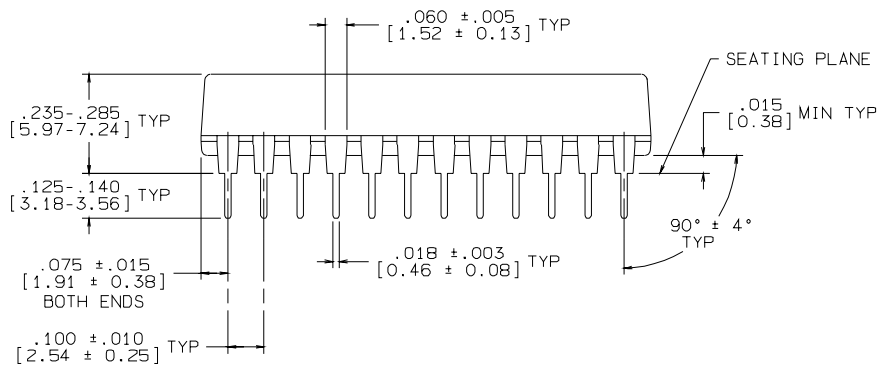
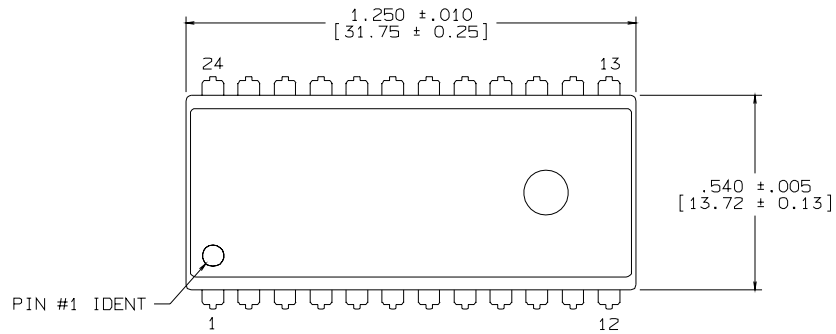


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10054	09/24/93	TL/MP
B	NOTE 1: TIN/LEAD WAS 63/37; DEL PIN 1 ID HALF NOTCH; LD THICK WAS .010; 170 WAS .160; .225 WAS .210	10263	12/10/93	TL/MP
C	.235-.285 WAS .225-.260	10389	04/12/94	TL/MP
D	mm VALUE 31.75 WAS 3.18; CHANGE DWG SIZE FROM B TO C.	11378	02/26/96	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES/ 5.08 MICROMETERS MINIMUM
TIN/LEAD: 85/15 ON COPPER.
- NO JEDEC REGISTRATION AS OF 09/29/93.

APPROVALS	DATE	National Semiconductor		
DRAWN T. LEQUANG	09/24/93	2900 Semiconductor dr, Santa Clara, CA 95052-8090		
DFTG. CHK.		MOLDED DIP, 24 LEAD, IPS1		
ENGR. CHK.				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-NA24F	D
INCH [MM]	DO NOT SCALE DRAWING		SHEET 1 OF 1	